

ABSTRACT

Provided is a mounting apparatus which enables high levels of both maintenance/improvement of product quality and reduction of product cost by reliably preventing accidental contact of a mounting part with a mounting target part while enhancing the productivity. In S1, a contact detection start position Hs0 is set. In S2, a chip holding tool chucks an electronic part. In S3, S4, the tool is moved to a transfer position A, and then the tool is lowered to the Hs0 from the transfer position A. In S5, after the tool is lowered to the Hs0, the lowering speed is changed to a contact detection speed. In S6, it is determined whether or not the electronic part has come into contact with a substrate. If the result of the determination is YES, in S7, the lowering of the tool is stopped. In S8, the actual contact position Hc is measured. In S9, the next contact detection start position Hs1 is set, and Hs1 is set to Hs0 (Hs0-Hs1) so that the later steps reflect this setting. In S10, S11, after the electronic part is joined to the substrate by ultrasonic bonding, the tool is transferred to the transfer position A. In S12, it is determined whether or not a stop command is issued. If the result is YES, this flow is ended. If NO, the procedure returns to S2, and bonding is repeated.